Service of the Service of

COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

INTEGRATED CHIP PACKAGE STRUCTURE USING METAL SUBSTRATE AND METHOD OF MANUFACTURING THE SAME

	11.2	110, 20,070,110 11,20			
the specification of w	hich				
		and was amended o		· •	
as Application S	Serial No	and was amended d	n		
specification, including a cknowledge application in accordant hereby claim from application(s) for patential application(s).	g the claims, as amend the duty to disclose in ance with Title 37, Code oreign priority benefits tent or inventor's certion patent or inventor's certion	and understand the conded by any amendment reference of Federal Regulations, § under Title 35, Untied States listed below and har entificate having a filing date	erred to above al to the pate 1.56(a). les Code, §11 live also ident	ntability of this 9 of any foreign	
Number	Country	Date Filed(yyyy/mm/dd)	Yes	No	
90133194	Taiwan, R.O.C.	2001/12/31	X		
	n the Patent and Trade (Reg. No. 43,3:	36) Chanette Armstror	rewith: (Reg. No	. 39,081)	
SEND CORRESPONDENCE TO:		- · · · · 	DIRECT TELEPHONE CALLS TO: (Name and telephone number)		
J.C. Patents, Inc. 4 Venture, Suite 250, Irvine, CA 92618 (949) 660-0761			Jiawei Huang (949) 660-0762		

Single March States

COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature S

1/18/2002

Sole or First Joint Inventor: Mou-Shiung Lin

Citizenship: U.S.A.

Residence and Post Office Address: No. 28, Chin-Shan St. X, Hsinchu, Taiwan, R.O.C.

Sin-Tuan Ros

1/18/02

Signature

Date

Second Joint Inventor (if any): Jin-Yuan Lee

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address: No. 11, Lane 4, An-Ho St., Hsinchu, Taiwan, R.O.C.

Signature

Date

Third Joint Inventor (if any): Ching-Cheng Huang

Citizenship: Taiwan, R,O,C.

Residence and Post Office Address: 11F-1, No. 38-24, Lane 72, Kuanghua II St., Hsinchu, Taiwan, R.O.C.